

ABSTRACT

2 A packaging process for improving effective chip-bonding area is disclosed in the
3 present invention. An A-stage liquid paste is formed on a substrate and partially cured
4 to become a B-stage film layer. The B-stage film layer is maintained without fully
5 cured passing through a chip-attaching step and an electrically connecting step. During
6 the molding step, the packing pressure for the molding compound (1000psi~1500psi) is
7 larger than the chip attaching pressure for enabling the B-stage film layer to be closely
8 compressed in order to improve effective chip-bonding area. The B-stage film layer and
9 the molding compound are cured simultaneous in the molding step.

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